WHAT IS CLAIMED IS:

1. A laser processing apparatus comprising:

a chuck table having a holding surface configured to hold a workpiece;

a laser oscillator configured to oscillate a laser;

a first condenser configured to condense a laser beam emitted from the laser oscillator, and irradiate the workpiece held on the chuck table with the laser beam; and

an observing unit configured to observe a state of a condensing point of the laser beam applied to the workpiece in a pseudo manner;

the observing unit including

a second condenser configured to condense the laser beam in a direction perpendicular or parallel to the holding surface of the chuck table,

a microscope configured to magnify the laser beam condensed by the second condenser,

an imaging element configured to observe and image the condensing point of the laser beam magnified by the microscope, and

a control unit configured to determine whether the state of the condensing point of the laser beam observed by the imaging element is acceptable or

not, wherein

when it is determined that the state of the condensing point of the laser beam is not acceptable,

optical parts of the laser processing apparatus are adjusted while the image of the condensing point of the laser beam imaged by the imaging element is checked; and

when it is determined that the state of the condensing point of the laser beam is acceptable, the adjustment of the optical parts is ended.

2. The laser processing apparatus according to claim 1, wherein

the observing unit is configured to be detachable.

3. The laser processing apparatus according to claim 1, wherein

the control unit is configured to determine whether the state of the condensing point of the laser beam observed by the imaging element is acceptable or not by determining whether or not a shape and luminance distribution of the condensing point of the image imaged by the imaging element are within a preset range.

4. An observing method of observing a state of a laser beam applied to a workpiece in a pseudo manner in a laser processing apparatus including a chuck table having a holding surface configured to hold the workpiece, a

laser oscillator configured to oscillate a laser, and a first condenser configured to condense the laser beam emitted from the laser oscillator, and irradiate the workpiece held on the chuck table with the laser beam, the observing method comprising:

a preparing step of preparing an observing unit including a second condenser configured to condense the laser beam in a direction perpendicular or parallel to the holding surface of the chuck table, a microscope configured to magnify the laser beam condensed by the second condenser, and an imaging element configured to observe and image a condensing point of the laser beam magnified by the microscope;

a disposing step of disposing the observing unit in a position capable of receiving the laser beam emitted from the laser oscillator;

an observing step of observing a state of the condensing point of the laser beam emitted from the laser oscillator and incident on the imaging element; and

a determining step of determining whether the state of the condensing point of the laser beam observed in the observing step is acceptable or not,

wherein

in the determining step, when it is determined that

the state of the condensing point of the laser beam is not acceptable,

optical parts of the laser processing apparatus are adjusted while the image of the condensing point of the laser beam imaged by the imaging element is checked; and

when it is determined in the determining step that the state of the condensing point of the laser beam is acceptable, the adjustment of the optical parts is ended.

5. The laser beam observing method according to claim 4, wherein

in the determining step, a beam shape and a luminous intensity distribution at a processing point of the laser beam are determined on a basis of a shape and luminance distribution of the condensing point of the image imaged by the imaging element.